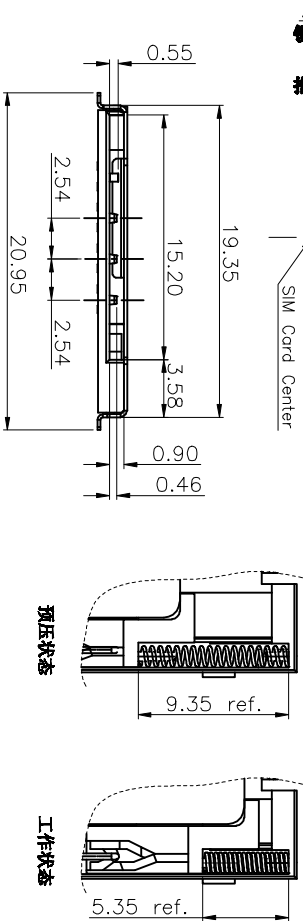
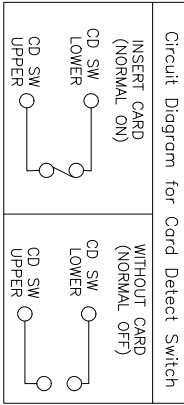
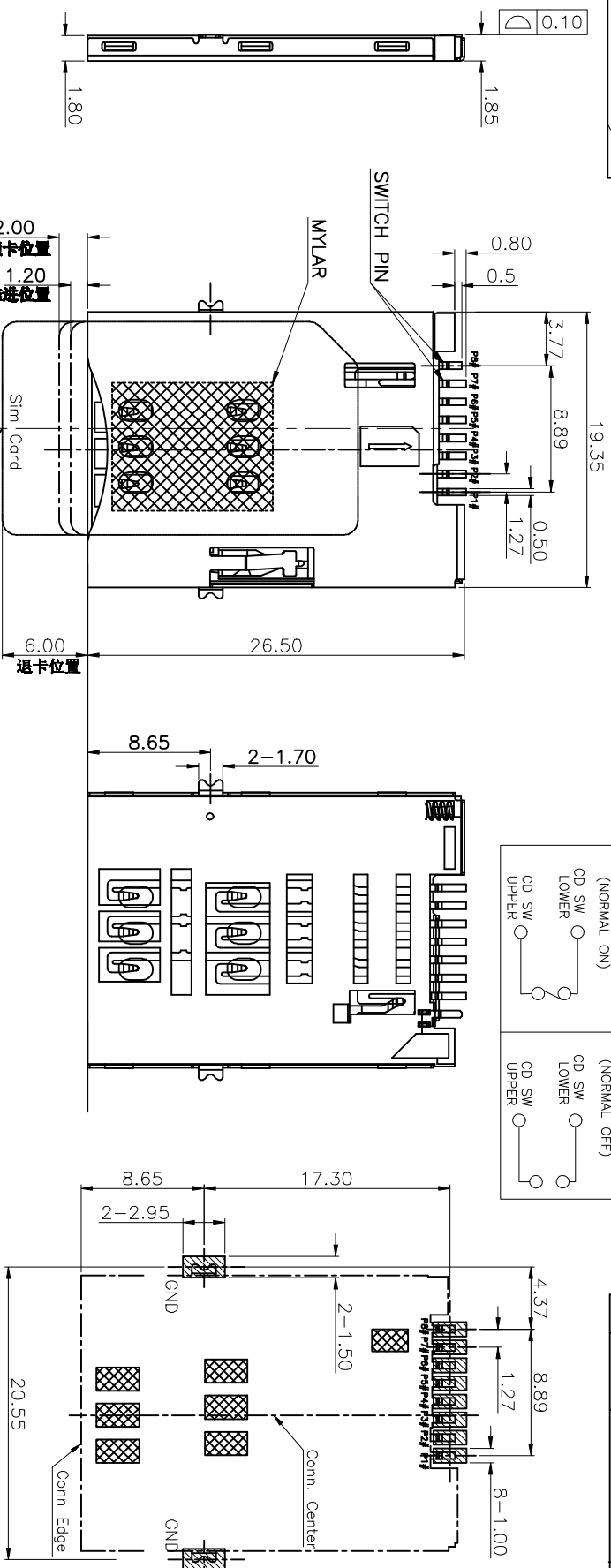
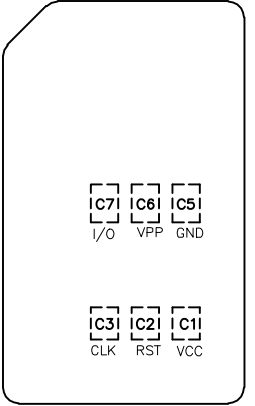


Customer drawings  
Reference only

REV.	ECN.NO.	MODIFY:CONTENT	DATE
A		NEW	2014/4/18



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05

SOLDER AREA  
 NONE CIRCUIT DIAGRAM AREA

NOTES:  
1)MATERIAL:  
HOUSING: LCP UL 94V-0  
CONTACT: C5210R-H,T=0.15  
SHELL: SUS201,T=0.20  
MYLAR: POLYESTER  
2)FINISH :  
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;  
ENTIRE CONTACT UNDERPLATED 50u"Min. NICKEL  
SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL,  
GOLD FLASH PLATED ON SOLDER TAILS  
3.INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

GENERAL TOLERANCE		图号	设计	审核	比例
X.±0.25	X.±5°	<b>HRK-SMD5-185-0016</b>			1:1
X.±0.20	X.±2°	PUSH SIM CARD 6+2PIN			mm
.XX±0.15	.XX±1°	1.80H 无注(加MYLAR)			
XXX±0.08	.XX±0.5°	料号	日期	2015/10/30	
SHEET 1/1					

深圳市迈睿康科技有限公司